03-29-02

RCE/28/00



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

KERFIAEI

Applicants:

Mike F. Chang et al.

EPR - 1 200

Assignee:

Siliconix incorporated

TC 2800 MAIL ROOM

Title:

Semiconductor Die Package Including Cup-Shaped Leadframe

Serial No.:

09/468,249

Filing Date:

December 10, 199

Examiner:

S. Rao

Group Art Unit:

2814

Docket No.:

M-7970 US

San Jose, California March 27, 2002

BOX RCE

COMMISSIONER FOR PATENTS

Washington, D. C. 20231

REQUEST FOR CONTINUED EXAMINATION (RCE)

Dear Sir:

This is a Request for Continued Examination (RCE) under 37 C.F.R. § 1.114 of the above-identified application.

Please consider the Response to Final Office Action and Petition for Extension of Time which accompanies this RCE.

The RCE fee required under 37 C.F.R. § 1.17(e) is authorized in an accompanying transmittal letter.

Please contact the undersigned attorney with any questions concerning this request or the above-identified patent application.

EXPRESS MAIL LABEL NO:

EL 937083 507 US

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Respectfully submitted,

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Application No. 09/468,249